High Current Surface Mount PNP Silicon Switching Transistor for Load Management in Portable Applications

Features

- NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS $(T_A = 25^{\circ}C)$

| Rating | Symbol | Value | Unit |
|--------------------------------|------------------|-------------|------|
| Collector - Emitter Voltage | V _{CEO} | -30 | Vdc |
| Collector - Base Voltage | V _{CBO} | - 50 | Vdc |
| Emitter - Base Voltage | V _{EBO} | -5.0 | Vdc |
| Collector Current – Continuous | I _C | -1.0 | Adc |
| Collector Current – Peak | I _{CM} | -2.0 | Α |

THERMAL CHARACTERISTICS

| Characteristic | Symbol | Max | Unit |
|--|-----------------------------------|-------------|-------------|
| Total Device Dissipation FR–5 Board, (Note 1) T _A = 25°C Derate above 25°C | P _D | 310 2.5 | mW mW/°C |
| Thermal Resistance Junction-to-Ambient (Note 1) | $R_{\theta JA}$ | 403 | °C/W |
| Total Device Dissipation Alumina Substrate, (Note 2) T _A = 25°C Derate above 25°C | P _D | 710 5.7 | mW mW/°C |
| Thermal Resistance Junction-to-Ambient (Note 2) | $R_{\theta JA}$ | 176 | °C/W |
| Total Device Dissipation (Ref. Figure 8) (Single Pulse < 10 sec.) | P _{Dsingle} | 575 | mW |
| Junction and Storage Temperature | T _J , T _{stg} | -55 to +150 | °C |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 1. FR-4 @ Minimum Pad
- 2. FR-4 @ 1.0 X 1.0 inch Pad



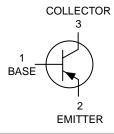
ON Semiconductor®

www.onsemi.com

30 VOLTS, 2.0 AMPS PNP TRANSISTORS



SOT-23 (TO-236) CASE 318 STYLE 6



MARKING DIAGRAM



G3 = Device Code

M = Date Code*

= Pb-Free Package

(Note: Microdot may be in either location)
*Date Code orientation and/or overbar may vary depending upon manufacturing location.

ORDERING INFORMATION

| Device | Package | Shipping [†] |
|----------------|---------------------|------------------------|
| MMBT589LT1G | SOT-23 (Pb-Free) | 3,000 / Tape & Reel |
| NSVMMBT589LT1G | SOT-23 (Pb-Free) | 3,000 / Tape & Reel |

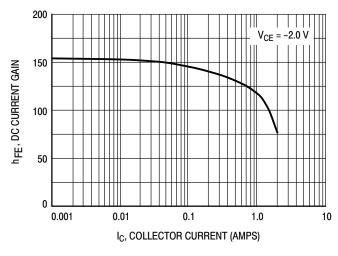
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

| Characteristic | Symbol | Min | Max | Unit | |
|---|-----------------------|------------------------|-------------------------|------|--|
| OFF CHARACTERISTICS | | | | | |
| Collector – Emitter Breakdown Voltage $(I_C = -10 \text{ mAdc}, I_B = 0)$ | V _(BR) CEO | -30 | _ | Vdc | |
| Collector – Base Breakdown Voltage $(I_C = -0.1 \text{ mAdc}, I_E = 0)$ | V _(BR) CBO | -50 | - | Vdc | |
| Emitter – Base Breakdown Voltage (I _E = -0.1 mAdc, I _C = 0) | V _{(BR)EBO} | -5.0 | - | Vdc | |
| Collector Cutoff Current (V _{CB} = -30 Vdc, I _E = 0) | Ісво | _ | -0.1 | μAdc | |
| Collector–Emitter Cutoff Current (V _{CES} = -30 Vdc) | I _{CES} | _ | -0.1 | μAdc | |
| Emitter Cutoff Current (V _{EB} = -4.0 Vdc) | I _{EBO} | _ | -0.1 | μAdc | |
| ON CHARACTERISTICS | | | | | |
| DC Current Gain (Note 3) (Figure 1) $ \begin{aligned} &(I_C = -1.0 \text{ mA, } V_{CE} = -2.0 \text{ V}) \\ &(I_C = -500 \text{ mA, } V_{CE} = -2.0 \text{ V}) \\ &(I_C = -1.0 \text{ A, } V_{CE} = -2.0 \text{ V}) \\ &(I_C = 2.0 \text{ A, } V_{CE} = -2.0 \text{ V}) \end{aligned} $ | h _{FE} | 100 100 80 40 | - 300 - - | - | |
| Collector – Emitter Saturation Voltage (Note 3) (Figure 3) $ \begin{pmatrix} I_C = -0.5 \text{ A}, I_B = -0.05 \text{ A} \end{pmatrix} $ $ \begin{pmatrix} I_C = -1.0 \text{ A}, I_B = 0.1 \text{ A} \end{pmatrix} $ $ \begin{pmatrix} I_C = -2.0 \text{ A}, I_B = -0.2 \text{ A} \end{pmatrix} $ | V _{CE(sat)} | - - - | -0.25 -0.30 -0.65 | V | |
| Base – Emitter Saturation Voltage (Note 3) (Figure 2) $(I_C = -1.0 \text{ A}, I_B = -0.1 \text{ A})$ | V _{BE(sat)} | _ | -1.2 | V | |
| Base – Emitter Turn–on Voltage (Note 3) (I _C = -1.0 A, V _{CE} = -2.0 V) | V _{BE(on)} | - | -1.1 | V | |
| Cutoff Frequency ($I_C = -100 \text{ mA}$, $V_{CE} = -5.0 \text{ V}$, $f = 100 \text{ MHz}$) | f _T | 100 | _ | MHz | |
| Output Capacitance (f = 1.0 MHz) | Cobo | _ | 15 | pF | |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

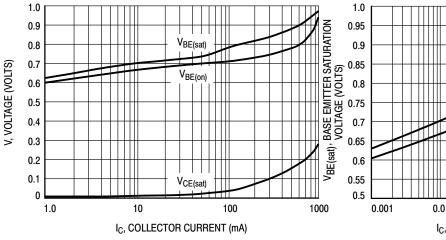
3. Pulsed Condition: Pulse Width = 300 msec, Duty Cycle ≤ 2%



230 $V_{CE} = -1.0 V$ 210 125°C 190 hFE, DC CURRENT GAIN 170 150 25°C 130 110 90 -55°C 70 50 1.0 10 100 1000 IC, COLLECTOR CURRENT (mA)

Figure 1. DC Current Gain versus **Collector Current**

Figure 2. DC Current Gain versus **Collector Current**



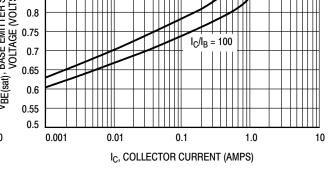
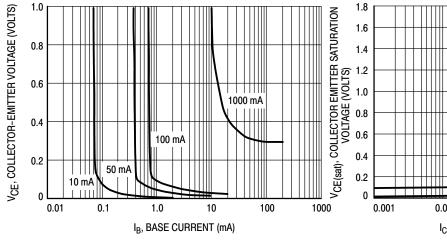


Figure 3. "On" Voltages

Figure 4. Base Emitter Saturation Voltage versus Collector Current

 $I_C/I_B = 100$



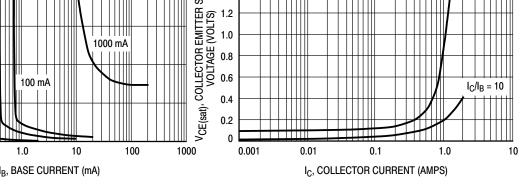


Figure 5. Collector Emitter Saturation Voltage versus Collector Current

Figure 6. Collector Emitter Saturation Voltage versus Collector Current

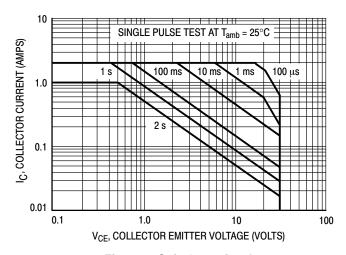


Figure 7. Safe Operating Area

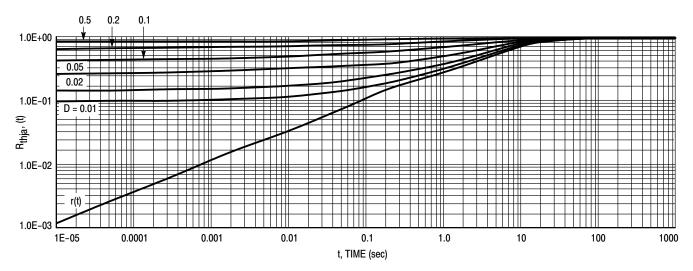
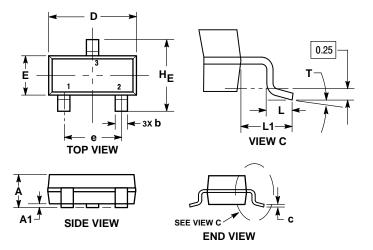


Figure 8. Normalized Thermal Response

PACKAGE DIMENSIONS

SOT-23 (TO-236) CASE 318-08 **ISSUE AR**



NOTES

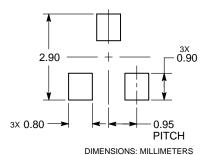
- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- CONTROLLING DIMENSION: MILLIMETERS.
 MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
- DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

| | MILLIMETERS | | | INCHES | | |
|-----|-------------|------|------|--------|-------|-------|
| DIM | MIN | NOM | MAX | MIN | NOM | MAX |
| Α | 0.89 | 1.00 | 1.11 | 0.035 | 0.039 | 0.044 |
| A1 | 0.01 | 0.06 | 0.10 | 0.000 | 0.002 | 0.004 |
| b | 0.37 | 0.44 | 0.50 | 0.015 | 0.017 | 0.020 |
| С | 0.08 | 0.14 | 0.20 | 0.003 | 0.006 | 0.008 |
| D | 2.80 | 2.90 | 3.04 | 0.110 | 0.114 | 0.120 |
| E | 1.20 | 1.30 | 1.40 | 0.047 | 0.051 | 0.055 |
| е | 1.78 | 1.90 | 2.04 | 0.070 | 0.075 | 0.080 |
| L | 0.30 | 0.43 | 0.55 | 0.012 | 0.017 | 0.022 |
| L1 | 0.35 | 0.54 | 0.69 | 0.014 | 0.021 | 0.027 |
| HE | 2.10 | 2.40 | 2.64 | 0.083 | 0.094 | 0.104 |
| T | 0° | | 10° | 0° | | 10° |

STYLE 6:

- PIN 1. BASE 2. EMITTER
 - COLLECTOR

RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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